## High Performance LGA Cooling Solutions\*

## DIGI-KEY PART # ATS1360-ND

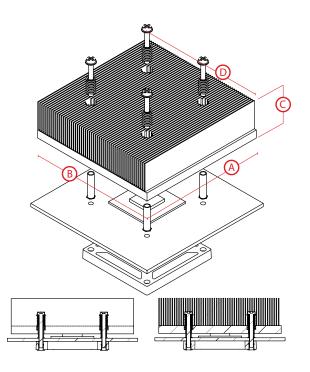
ATS PART # ATS-57003-C1-R0

## Features & Benefits

Provides high capacity cooling for high power LGAs

Unique attachment minimizes mechanical stress on the device

Includes stand-offs with springs, screws and backing plate for direct attachment to the PCB



| AIR VELOCITY |  |     |  | THERMAL RESISTANCE |               |  |
|--------------|--|-----|--|--------------------|---------------|--|
| FT/MIN       |  | M/S |  | °C/W (UNDUCTED)    | °C/W (DUCTED) |  |
| 200          |  | 1.0 |  | 1.38               | 0.8           |  |
| 300          |  | 1.5 |  | 0.87               |               |  |
| 400          |  | 2.0 |  | 0.7                |               |  |
| 500          |  | 2.5 |  | 0.6                |               |  |
| 600          |  | 3.0 |  | 0.55               |               |  |
| 700          |  | 3.5 |  | 0.5                |               |  |
| 800          |  | 4.0 |  | 0.45               |               |  |

## **Product Details**<sup>†</sup>

| DIMENSION A | DIMENSION B | DIMENSION C <sup>§</sup> | DIMENSION D | TIM <sup>≠</sup> | FINISH         |
|-------------|-------------|--------------------------|-------------|------------------|----------------|
| 94          | 94          | 27                       | 94          | NO TIM           | BLACK-ANODIZED |

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com** 

\* RoHS Compliant

**‡** TIM = Thermal Interface Material

† Dimensions are measured in millimeters

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method





**Thermal Performance Table**